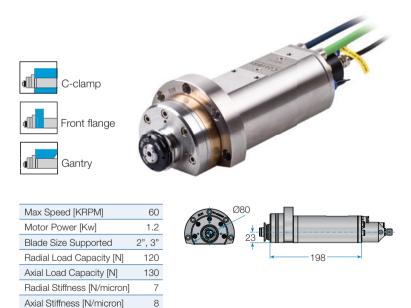


BOH 1.2 Kw, 60 KRPM

Weight [Kg]

The BOH spindle model supports various ranges of dicing application, such as IC's, Si & GaAs wafers, ceramics, opto-electronic components, LED's, medical sensors, PZT, and the like. This spindle was designed to deliver optimal performance at high spindle speed while maintaining exceptional stiffness and accuracy. When cut quality becomes a major process consideration, the BOH will be the most suitable spindle choice.



6.5